

Title (en)  
THREE-DIMENSIONAL ELECTRONIC DEVICE AND RELATIVE MANUFACTURE METHOD

Title (de)  
3D-ELEKTRONIKBAUTEIL UND SEINE HERSTELLUNGSMETHODE

Title (fr)  
DISPOSITIF ELECTRONIQUE TRIDIMENSIONNEL ET PROCEDE DE FABRICATION ASSOCIE

Publication  
**EP 1419529 A2 20040519 (EN)**

Application  
**EP 02733231 A 20020507**

Priority  
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• IT TO20010433 A 20010508

Abstract (en)  
[origin: WO02091469A2] There is described a three-dimensional electronic device (10) having a first and a second electronic circuit (12, 14) stacked one on top of the other and having respective contact pads (22); and a substantially C-shaped spacer member (26) made of electrically conducting material and extending between the first and second electronic circuit (12, 14) to connect a first contact pad (22a) of the first integrated circuit (12) electrically to a second contact pad (22b) of the second integrated circuit (14).

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**H01L 25/065**; H01L 25/10; H01L 21/98

IPC 8 full level  
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CPC (source: EP)  
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C-Set (source: EP)  
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